Product Change Notification / BLAS-15TNDI621

Date:

15-Dec-2023

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6761 Initial Notice: Qualification of ATP7 as an additional assembly site for SST26VF032B-104I/TD, SST26VF032BT-104I/TD, SST26WF064C-104I/TD, SST26WF064CT-104I/TD, SST26VF064B-104I/TD and SST26VF064BT-104I/TD catalog part numbers (CPN) available in 24L TBGA (6x8x1.2mm) package.

Affected CPNs:

BLAS-15TNDI621_Affected_CPN_12152023.pdf
BLAS-15TNDI621_Affected_CPN_12152023.csv

Notification Text:

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ATP7 as an additional assembly site for SST26VF032B-104I/TD, SST26VF032BT-104I/TD, SST26WF064C-104I/TD, SST26WF064CT-104I/TD, SST26VF064B-104I/TD and SST26VF064BT-104I/TD catalog part numbers (CPN) available in 24L TBGA (6x8x1.2mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Lingsen Precision Industries, LTD. (LPI)	Lingsen Precision Industries, LTD. (LPI)	Amkor Technology Philippines (P3/P4), INC. (ATP7)
Substrate Core Material	HL832NXA	HL832NXA	HL832NXA
Substrate SM Material	AUS308	AUS308	AUS308
Substrate L1/L2 Thickness	20/20um	20/20um	12/12um
Substrate SM Thickness	25+/-10um	25+/-10um	30um
Wire Material	Au	Au	Au
Die Attach Material	2100A	2100A	Ablebond 2300
Molding Compound Material	G770HT	G770HT	G770FE
Solder Ball Material	SAC405	SAC405	SAC405

Impacts to Data Sheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying ATP7 as an additional assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: May 2024

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	December 2023						>	May 2024				
Workweek	48	49	50	51	52	53		18	19	20	21	22
Initial PCN Issue			x									

Date												
Qual Report Availability								x				
Final PCN Issue Date								x				

Method to Identify Change: Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: December 15, 2023: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_BLAS-15TNDI621 Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

SST26VF032B-104I/TD
SST26VF032BT-104I/TD
SST26WF064C-104I/TD
SST26WF064CT-104I/TD
SST26VF064B-104I/TD
SST26VF064BT-104I/TD